| Association connecting<br>Description connecting<br>Electronics industries<br>Material Composition Declaration<br>© Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both<br>international and Pan-American copyright conventions. |                              |                            |                           | This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility. |                         |                     |   |                 |                                 |                                     |     |           |  |
|---|------------------------------|----------------------------|---------------------------|---|-------------------------|---------------------|---|-----------------|---------------------------------|-------------------------------------|-----|-----------|--|
|   |                              |                            | Form Type<br>Distribute   |   |                         |                     |   | d Mfg Informati | on                              |                                     |     |           |  |
| Supplier Information  |                              |                            |                           |   |                         |                     |   |                 |                                 |                                     |     |           |  |
| Company name* Comp  |                              |                            | ompany unique ID          |   |                         | Unique ID Authority |   |                 |                                 | Response Date*                      |     |           |  |
| onsemi  |                              |                            |                           |   |                         |                     |   |                 |                                 | 2023-06-12                          |     |           |  |
| Contact Name Title - Contact  |                              |                            | ct                        |   | Phone - Contact*        |                     |   | Ema             | Email - Contact*                |                                     |     |           |  |
| Product-Env-Stewards Product Env  |                              |                            | Enviro Compliance         |   | NA                      |                     |   | Pro             | Product-Env-Stewards@onsemi.com |                                     |     |           |  |
| Authorized Representative* Title - Rep  |                              |                            | epresentative             |   | Phone - Representative* |                     |   | Ema             | Email - Representative*         |                                     |     |           |  |
| Product-Env-Stewards F  |                              |                            | Product Enviro Compliance |   |                         | NA                  |   |                 | Pro                             | Product-Env-Stewards@onsemi.com     |     |           |  |
| Requester Item Number   | Number Mfr Item Nu           |                            | Number Mfr Item Name      |   |                         | Effective Date      | Version                                     | Manufacturing   | Site                            | Weight*                             | UOM | Unit Type |  |
|   | ESD9L3                       | ESD9L3.3ST5G ESD PROT DIOD |                           | DE UNI SOD923   | 3                       | 2023-06-12          |   | CN1             | CN1                             |                                     | mg  | Each      |  |
| Manufacturing Proccess Informa  | tion                         |                            |                           |   |                         |                     |   |                 |                                 |                                     |     |           |  |
| Terminal Plating / Grid Array M   | Material Terminal Base Alloy |                            | Alloy J                   | -STD-020 MSL  | Rating                  | Peak Proce          | k Process Body Temperature Max Time at Peak |                 | at Peak Temp                    | Temperature Number of Reflow Cycles |     | cles      |  |
| Matte Tin (Sn) - annealed CU Alloy  |                              | 1                          | l                         |   | 260                     | С                   | 30  | se              | econds 3                        |                                     |     |           |  |
| Comments  |                              |                            |                           |   |                         |                     |   |                 |                                 |                                     |     |           |  |
| evel 1 - maximum time at peak temperat  | ure during so                | ldering is 10-3            | 0 seconds                 |   |                         |                     |   |                 |                                 |                                     |     |           |  |
| for more information regarding material   | composition                  | please refer to            | page 3                    |   |                         |                     |   |                 |                                 |                                     |     |           |  |

| RoHS Material Composition Declaration  |  |  |   | Declaration Type *                              | Detailed  |  |  |  |  |  |  |
|--|--|--|---|---|---|--|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS<br>Directive 2011/65/EU  | RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP). |  |   |   |   |  |  |  |  |  |  |
| cadmium, hexavalentchromium, polybrominate<br>contains a RoHS restricted substance inexcess<br>encompass all such components. Supplier certif<br>as of the date that Supplier completes this form<br>Company acknowledges that Supplier may hav<br>independently verified information provided by<br>certification in this paragraph. If the Company a | ed biphenyls and/or polybrominated dip<br>of an applicable quantity limit, please ir<br>ies that it gathered the information it pro-<br>.Supplier acknowledges that Company<br>e relied on informationprovided by othe<br>v others, Supplier agrees that, at a minin<br>and the Supplier enter into a written agre<br>pource of the Supplier's liability and the   | henyl ethers (each a "<br>ndicate below which, i<br>ovides in this form us<br>will rely on this certifiers<br>in completing this<br>num, itssuppliers have<br>eement with respect to<br>Company's remedies | RoHS restricted substance") in exce<br>if any, RoHS exemption you believe<br>ing appropriate methods to ensure if<br>ication in determining the complian<br>form, and that Supplier may not have<br>e provided certifications regarding the<br>to the identified part, the terms and co<br>for issues that arise regarding inform | ce of its products with European Union membe    | ove. If a homogeneous material within the part<br>er level components, the declaration shall<br>l correct to the best of its knowledge and belief,<br>r state laws that implement the RoHS Directive.<br>wever, in situations where Supplier has not<br>tions are at least as comprehensive as the<br>anty rights and/or remedies provided as part of |  |  |  |  |  |  |
| RoHS Declaration * 1 - Item(s)   | does not contain RoHS restricted substa  | on above   | Supplier Acceptance   | * Accepted                                      |   |  |  |  |  |  |  |
| Exemption: If the declared item does not con applicable exemptions.  | ntain RoHS restricted substances per   | the definition above   | except for defined RoHS exempti   | ons, then select the corresponding response i   | n the RoHS Declaration above and choose all   |  |  |  |  |  |  |
| Exemption List Version   | EL-2011/534/EU   |  |   |   |   |  |  |  |  |  |  |
| Declaration Signature  |  |  |   |   |   |  |  |  |  |  |  |
| Instructions: Complete all of the required fin<br>Requester) and click on Submit Form to have  | elds on all pages of this form. Select the form returned to the Requester  | he "Accepted" on th  | e Supplier Acceptance drop-down   | . This will display the signature area. Digital | lly sign the declaration (if required by the  |  |  |  |  |  |  |
| Supplier Digital Signature Ra  | stislav Drska  | Le   |   |   |   |  |  |  |  |  |  |

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

| sigma range of distribution unless | otherwise noted). |                 |          |                              | -          | -      |        | -               |
|------------------------------------|-------------------|-----------------|----------|------------------------------|------------|--------|--------|-----------------|
| Homogeneous Material               | Weight            | Unit of Measure | Level    | Substance                    | CAS        | Exempt | Weight | Unit of Measure |
| Die                                | 0.03              | mg              | Supplier | Silicon (Si)                 | 7440-21-3  |        | 0.03   | mg              |
| Lead Frame                         | 0.21              | mg              | Supplier | Silver (Ag)                  | 7440-22-4  |        | 0.0374 | mg              |
|                                    |                   |                 | В        | Nickel (Ni)                  | 7440-02-0  |        | 0.0649 | mg              |
|                                    |                   |                 | Supplier | Iron (Fe)                    | 7439-89-6  |        | 0.0897 | mg              |
|                                    |                   |                 | Supplier | Copper (Cu)                  | 7440-50-8  |        | 0.0181 | mg              |
| Mold Compound-Black                | 0.19              | mg              | Supplier | Ortho Cresol Novolac Resin   | 29690-82-2 |        | 0.019  | mg              |
|                                    |                   |                 | Supplier | Carbon Black (C)             | 1333-86-4  |        | 0.0009 | mg              |
|                                    |                   |                 | Supplier | Aluminum Hydroxide (Al(OH)3) | 21645-51-2 |        | 0.0275 | mg              |
|                                    |                   |                 | Supplier | Fused Silica (SiO2)          | 60676-86-0 |        | 0.1235 | mg              |
|                                    |                   |                 | Supplier | Phenolic Resin (Novolac)     | 9003-35-4  |        | 0.019  | mg              |
| Plating                            | 0.01              | mg              | Supplier | Tin (Sn)                     | 7440-31-5  |        | 0.01   | mg              |
| Wire Bond - Cu                     | 0.003             | mg              | Supplier | Copper (Cu)                  | 7440-50-8  |        | 0.003  | mg              |